

62mm Half Bridge IGBT Module

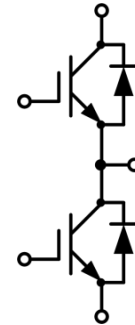
$V_{CES} = 1200V$, $I_C = 600A$, $V_{CE(sat)} = 1.82V$

Features

- 1200V Trench/Field Stop Technology
- Low switching losses
- V_{cesat} has a positive temperature coefficient

Applications

- UPS Systems
- Motor Drivers
- Three-level Application
- Servo Drivers



IGBT, Inverter Maximum Ratings

Parameter	Symbol	Test Condition	Value	Unit
Collector-Emitter voltage	V_{CES}	$T_{vj}=25^{\circ}C$	1200	V
Continuous DC collector current	$I_{C\ nom}$	$T_C=100^{\circ}C$, $T_{vj\ max}=175^{\circ}C$	600	A
Repetitive peak collector current	I_{CRM}	$t_P=1ms$	1200	A
Total power dissipation	P_{tot}	$T_C=25^{\circ}C$, $T_{vj\ max}=175^{\circ}C$	2050	W
Gate emitter voltage	V_{GE}		± 20	V

Characteristics Values

Parameter	Symbol	Test Condition	Value			Unit		
			Min.	Typ.	Max.			
Collector-Emitter saturation voltage	V_{CEsat}	$V_{GE}=15V$, $I_C=600A$ $V_{GE}=15V$, $I_C=600A$ $V_{GE}=15V$, $I_C=600A$		$T_{vj}=25^{\circ}C$ $T_{vj}=125^{\circ}C$ $T_{vj}=150^{\circ}C$	1.82 2.18 2.29	2.6	V	
Gate-Emitter threshold voltage	$V_{GE(th)}$	$I_C=12mA$, $V_{GE}=V_{CE}$		$T_{vj}=25^{\circ}C$	5.2	5.8	6.4	
Gate charge	Q_G	$V_{GE}=-15V \dots +15V$			7.52		μC	
Internal gate resistor	R_{Gint}			$T_{vj}=25^{\circ}C$	0.9		Ω	
Input capacitance	C_{ies}	$f=100KHz$, $V_{CE}=25V$, $V_{GE}=0V$		$T_{vj}=25^{\circ}C$	94.9		nF	
Reverse transfer capacitance	C_{res}				0.39		nF	
Collector-emitter cut-off current	I_{CES}	$V_{CE}=1200V$, $V_{GE}=0V$		$T_{vj}=25^{\circ}C$		2	mA	
Gate-emitter leakage current	I_{GES}	$V_{CE}=0V$, $V_{GE}=20V$		$T_{vj}=25^{\circ}C$		200	nA	
Turn-on delay time	$t_{d\ on}$	$I_C=600A$, $V_{CE}=600V$ $V_{GE}=\pm 15V$, $R_G=0.5\Omega$ (inductive load)		$T_{vj}=25^{\circ}C$ $T_{vj}=125^{\circ}C$ $T_{vj}=150^{\circ}C$	366 393 396		ns	

Rise time	t_r	$I_C=600A, V_{CE}=600V$ $V_{GE}=\pm 15V, R_G=0.5\Omega$ (inductive load)	$T_{vj}=25^\circ C$ $T_{vj}=125^\circ C$ $T_{vj}=150^\circ C$		86 98 101		
Turn-off delay time	$t_{d\ off}$	$I_C=600A, V_{CE}=600V$ $V_{GE}=\pm 15V, R_G=0.5\Omega$ (inductive load)	$T_{vj}=25^\circ C$ $T_{vj}=125^\circ C$ $T_{vj}=150^\circ C$		397 444 461		ns
Fall time	t_f	$I_C=600A, V_{CE}=600V$ $V_{GE}=\pm 15V, R_G=0.5\Omega$ (inductive load)	$T_{vj}=25^\circ C$ $T_{vj}=125^\circ C$ $T_{vj}=150^\circ C$		124 215 243		
Turn-on energy loss per pulse	E_{on}	$I_C=600A, V_{CE}=600V$ $V_{GE}=\pm 15V, R_G=0.5\Omega$ $di/dt=4700A/\mu s$ ($T_{vj}=150^\circ C$) (inductive load)	$T_{vj}=25^\circ C$ $T_{vj}=125^\circ C$ $T_{vj}=150^\circ C$		28.54 49.61 59.54		mJ
Turn-off energy loss per pulse	E_{off}	$I_C=600A, V_{CE}=600V$ $V_{GE}=\pm 15V, R_G=0.5\Omega$ $dv/dt=4200V/\mu s$ ($T_{vj}=150^\circ C$)(inductive load)	$T_{vj}=25^\circ C$ $T_{vj}=125^\circ C$ $T_{vj}=150^\circ C$		55.75 71.68 77.16		
SC data	ISC	$V_{GE}\leq 15V, V_{CE}=800V$ $V_{CEmax}=V_{CES}-L_{sCE}\cdot di/dt,$ $t_p\leq 8\mu s$	$T_{vj}=150^\circ C$		2000		A
Thermal resistance, junction to case	R_{thJC}	per IGBT				0.065	K/W
Temperature under switching conditions	$T_{vj\ op}$			-40		150	$^\circ C$

Diode, Inverter Maximum Ratings

Parameter	Symbol	Test Condition	Value	Unit
Repetitive peak reverse voltage	V_{RRM}	$T_{vj}=25^\circ C$	1200	V
Continuous DC forward current	I_F		600	A
Repetitive peak forward current	I_{FRM}	$t_p=1ms$	1200	A
I^2t -value	I^2t	$t_p=10ms, \sin 180^\circ, T_{vj}=125^\circ C$	45000	A^2S

Characteristics Values

Parameter	Symbol	Test Condition	Value			Unit
			Min.	Typ.	Max.	
Forward voltage	V_F	$I_F=600A, V_{GE}=0V$ $I_F=600A, V_{GE}=0V$ $I_F=600A, V_{GE}=0V$	$T_{vj}=25^\circ C$ $T_{vj}=125^\circ C$ $T_{vj}=150^\circ C$	2.24 2.17 2.10	2.80	V
Peak reverse recovery current	I_{RM}	$I_F=600A,$ $-di_F/dt=4700A/\mu s$ ($T_{vj}=150^\circ C$) $V_R=600V, V_{GE}=-15V$	$T_{vj}=25^\circ C$ $T_{vj}=125^\circ C$ $T_{vj}=150^\circ C$	320 448 464		A
Recovered charge	Q_r	$I_F=600A,$ $-di_F/dt=4700A/\mu s$ ($T_{vj}=150^\circ C$) $V_R=600V, V_{GE}=-15V$	$T_{vj}=25^\circ C$ $T_{vj}=125^\circ C$ $T_{vj}=150^\circ C$	29.00 70.94 87.43		$^\circ C$
Reverse recovered energy	E_{rec}	$I_F=600A,$ $-di_F/dt=4700A/\mu s$ ($T_{vj}=150^\circ C$) $V_R=600V, V_{GE}=-15V$	$T_{vj}=25^\circ C$ $T_{vj}=125^\circ C$ $T_{vj}=150^\circ C$	12.25 27.93 34.12		mJ
Thermal resistance, junction to case	R_{thJC}	per diode			0.078	K/W
Temperature under switching conditions	$T_{vj\ op}$			-40	150	$^\circ C$

Characteristics Values(Module)

Parameter	Symbol	Test Condition	Value	Unit
Isolation test voltage	V _{ISOL}	RMS, f=50Hz, t=1min	4000	V
Internal isolation			Al ₂ O ₃	
Storage temperature	T _{stg}		-40	125
Mounting torque for modul mounting	M		3.0	6.0
Weight	W		325	g

Typical Characteristics

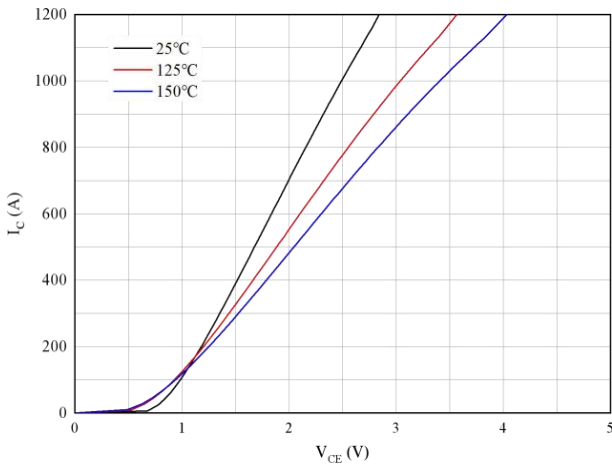


Fig 1. Typical output characteristics ($V_{GE}=15V$)

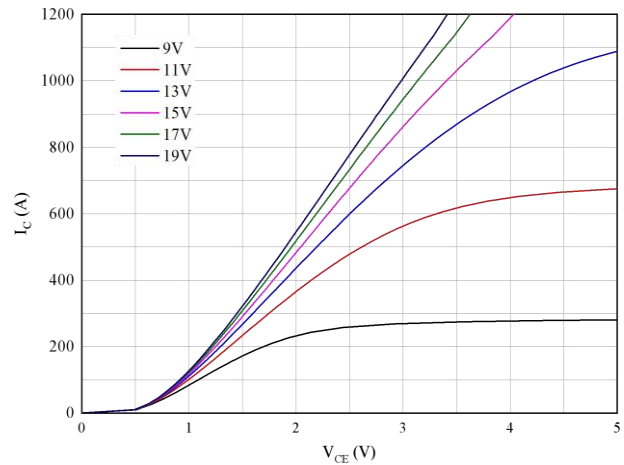


Fig 2. Typical output characteristics ($T_{vj}=150^{\circ}C$)

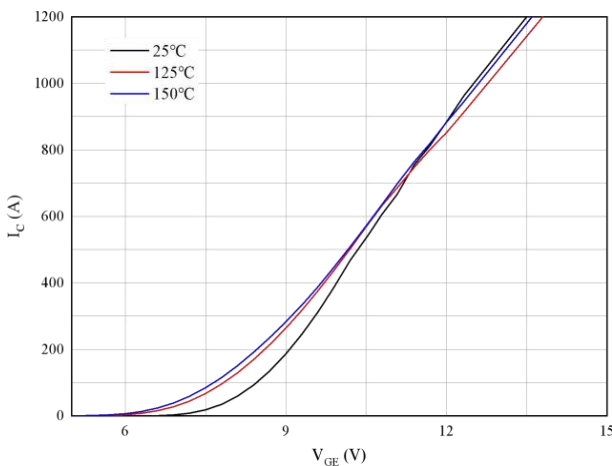


Fig 3. Typical transfer characteristic ($V_{CE}=20V$)

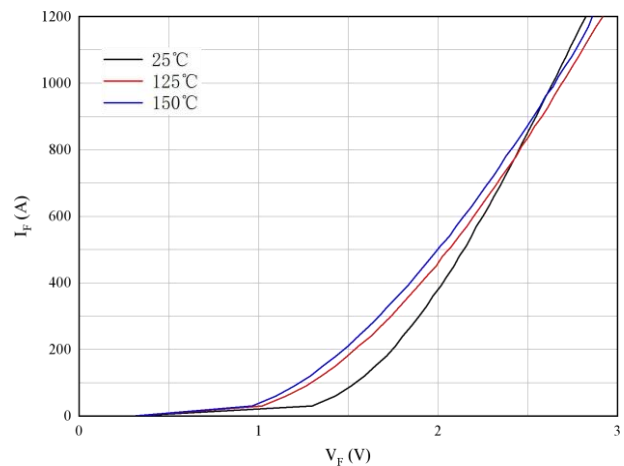


Fig 4. Forward characteristic of Diode

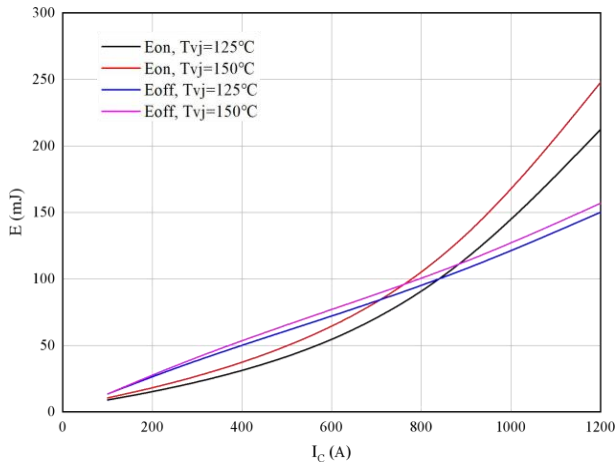


Fig 5. Switching losses of IGBT
 $V_{GE}=\pm 15\text{V}$, $R_{Gon}=0.5\Omega$, $R_{Goff}=0.5\Omega$, $V_{CE}=600\text{V}$

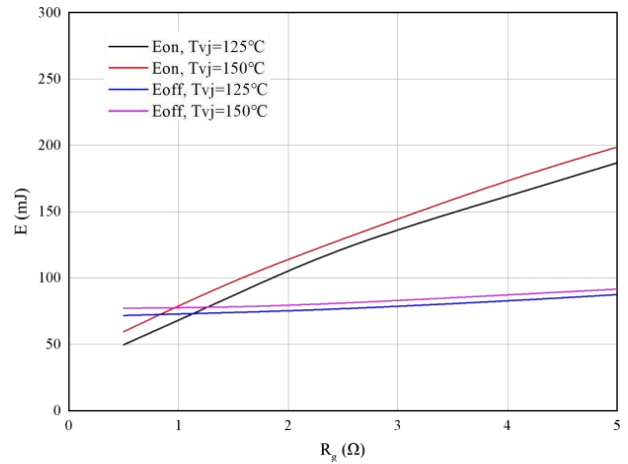


Fig 6. Switching losses of IGBT
 $V_{GE}=\pm 15\text{V}$, $I_C=600\text{A}$, $V_{CE}=600\text{V}$

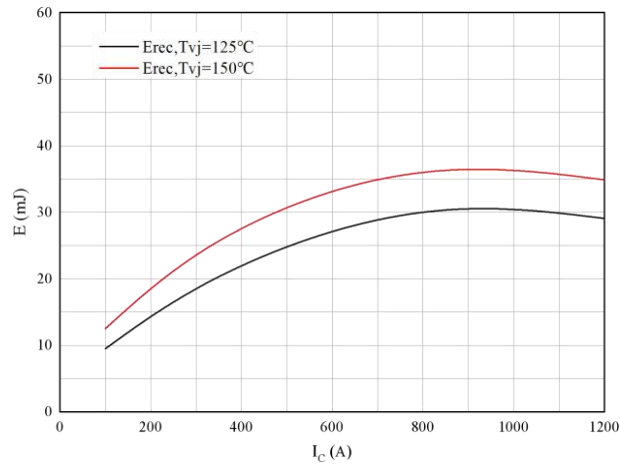


Fig 7. Switching losses of Diode
 $R_{Gon}=0.5\Omega$, $V_{CE}=600\text{V}$

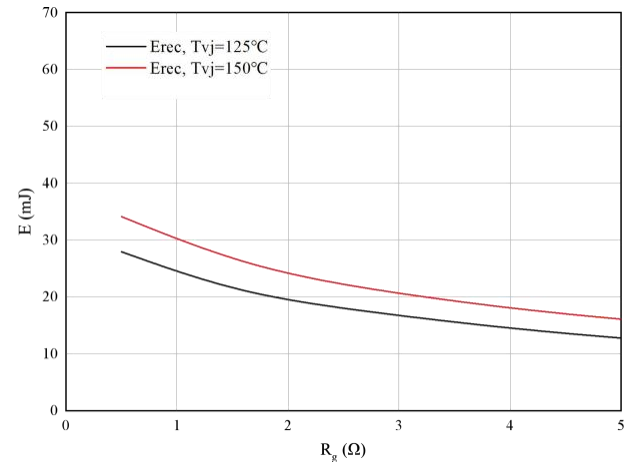


Fig 8. Switching losses of Diode
 $I_F=600\text{A}$, $V_{CE}=600\text{V}$

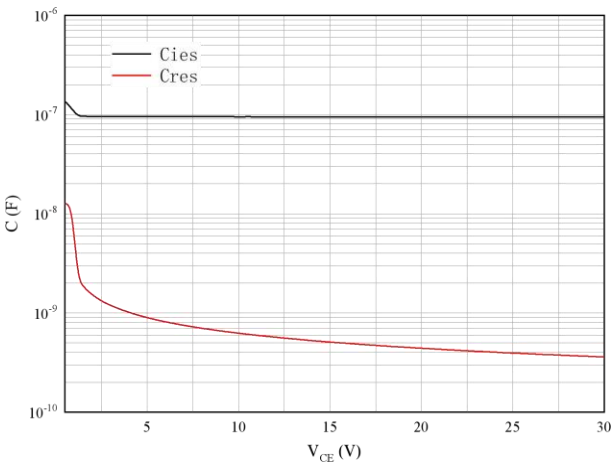


Fig 9. Capacitance characteristic

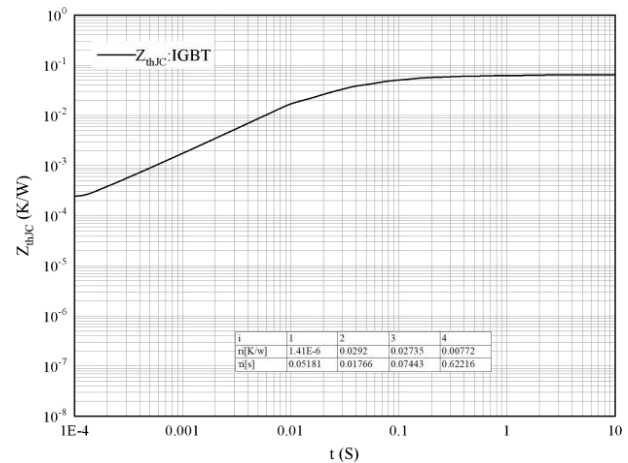


Fig 10. Transient thermal impedance IGBT, Inverter
 $Z_{thJC}=f(t)$

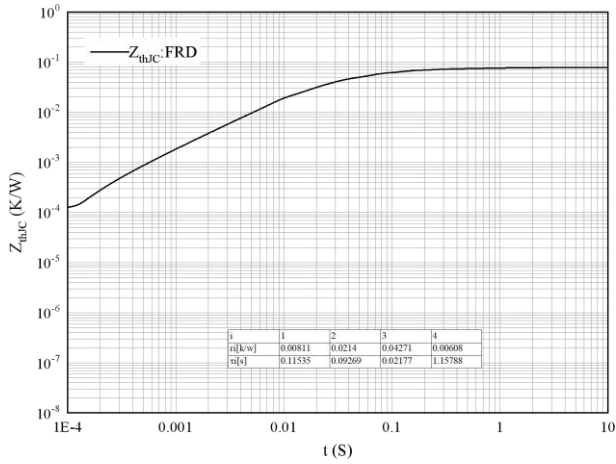
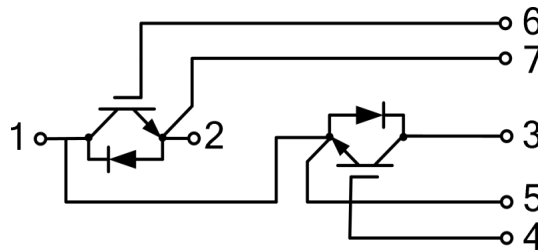
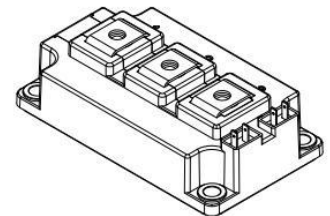
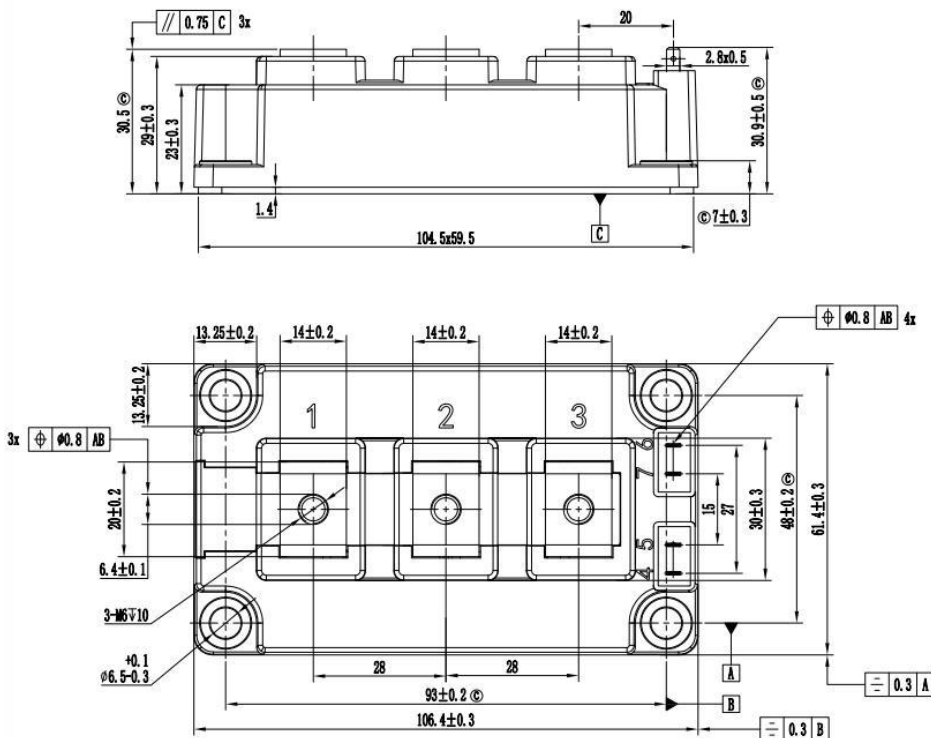


Fig 11. Transient thermal impedance FRD ,Inverter
 $Z_{thJC}=f(t)$

Circuit Diagram



Package Outlines(Unit: mm)



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